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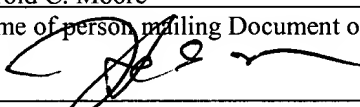
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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on August 6, 2003
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Harold C. Moore

Name of person mailing Document or Fee


Signature

August 6, 2003

Date of Signature

Re: Patent Application of: Charles E. May
Serial No.: 09/943,196
Filed: August 30, 2001
For: Arrangement and Method for Fabricating A
Semiconductor Wafer
Group Art Unit: 1765
Examiner: Lynette T. Umez-Eronini
Our Docket No.: 01-146 (1003-0606)

RULE 114 SUBMISSION AND
RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action dated May 6, 2003 for the above-identified patent application, please consider the following.